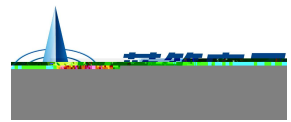


Rev.A Apr.-2022



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fi fi Žfi fi ! \$ ' & # / 0 # (- \$ fi

fi

fi fi Žfi fi 1 ! + 0 2 & ! \$ fi

With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process, HF Product.

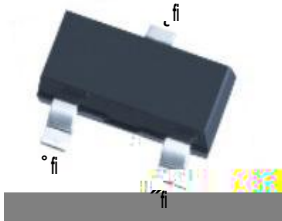
fi fi Žfi fi // / 3 # ' + 0 # (- \$ fi fi

Switching applications, interface circuit and driver circuit applications.

fi fi Žfi fi † 4 2 # " + 3 ! - 0 fi ' # & ' 2 # 0 fi



fi fi Žfi fi 5 # - - # - . fi



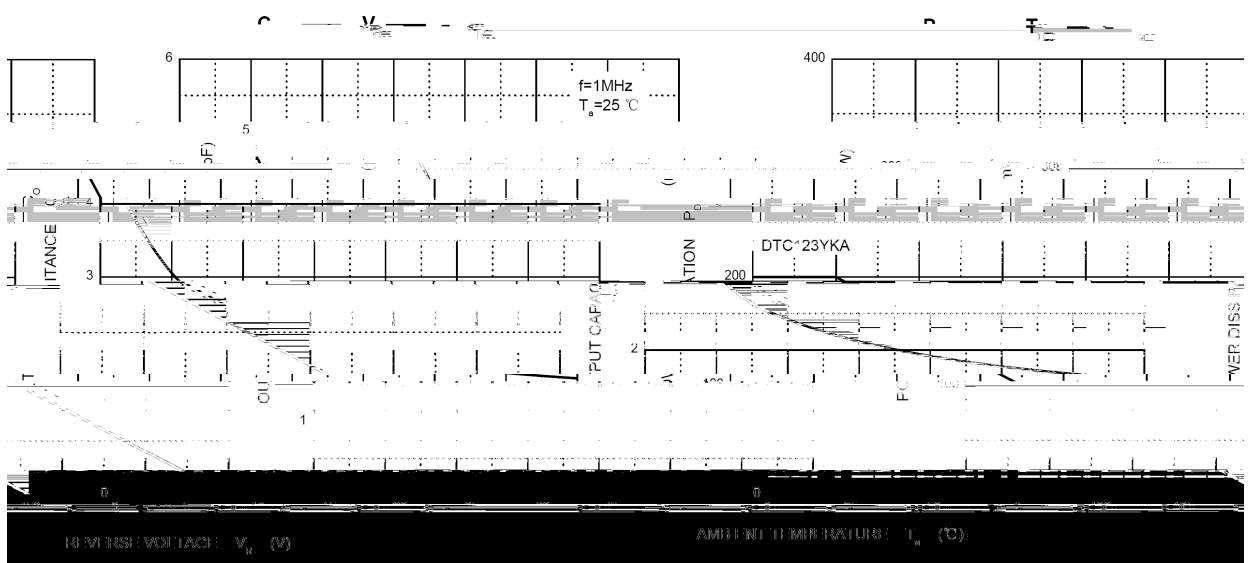
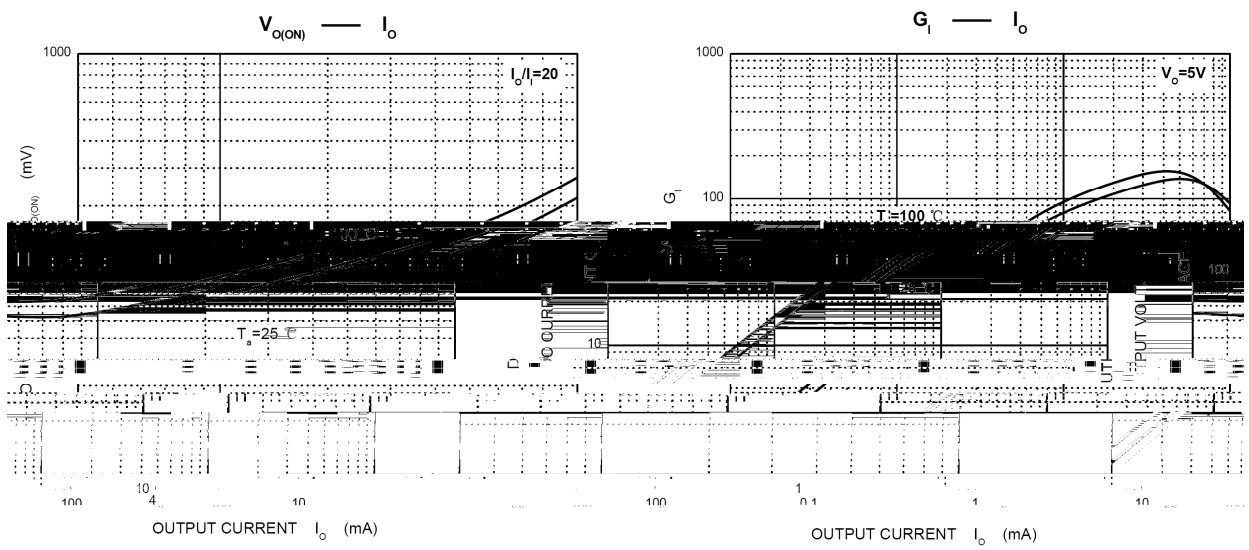
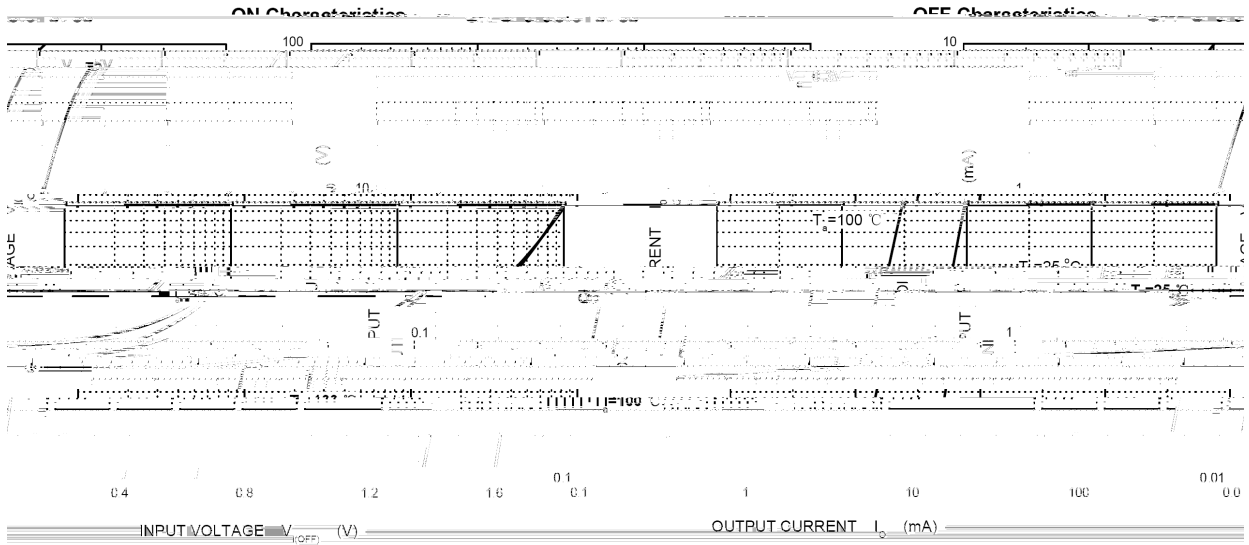
PIN 1 IN PIN 2 GND PIN 3 OUT

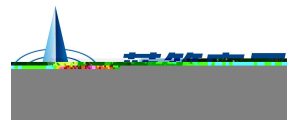
fi fi Žfi fi * + & , # - . fi

| | |
|---------|-----|
| Marking | H62 |
|---------|-----|

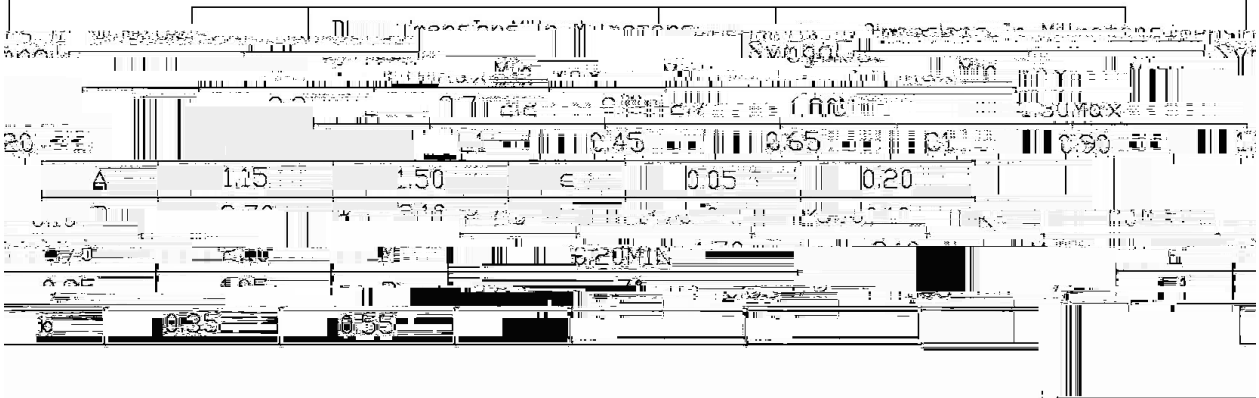
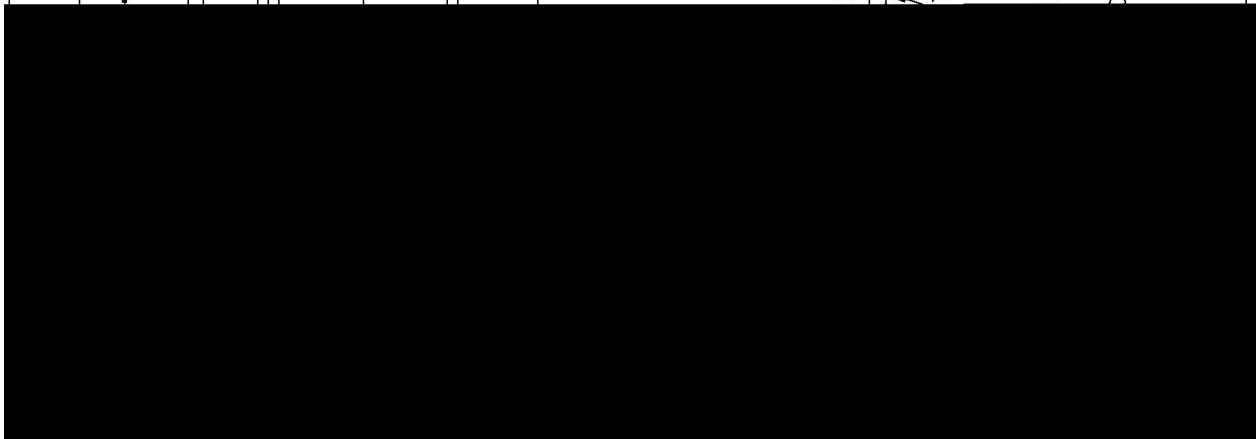
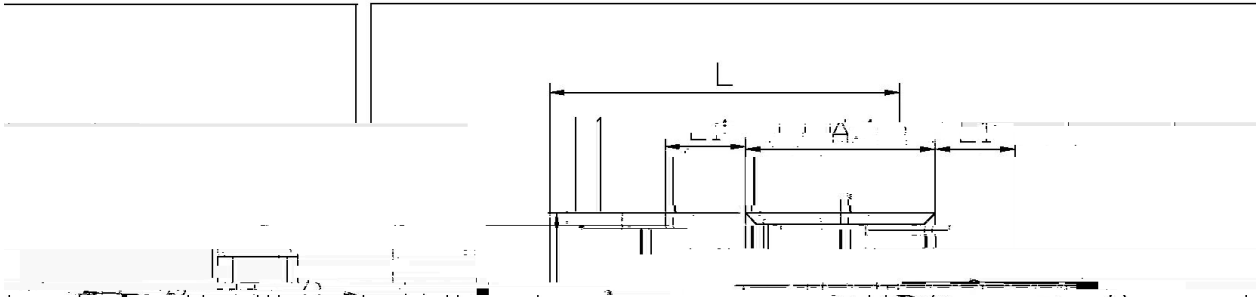


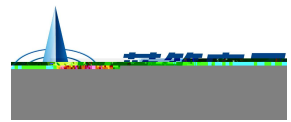
fs fi žfi fi †3! '0&#' +3fi ' =+&+ '0!&#S0#' fi ' 2&' !fi





fi fi Zfi fi 5+' ,+. !fi #8 !-\$#(- \$fi





9 温度曲线 Temperature Profile for IR Reflow Soldering(Pb-Free)

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Note:

- | | | | |
|---|---------|-----------|--|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

温度曲线 260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

温度曲线 5+ , +. # - . 15 ± 封装形式

/ REEL

(12.008())TJ ET. 3686.04 353.01 m3686.04 42629 | 53764 42629 53764 353.01 | h W* n BT58.04 0 0581400 Tm /F8 1 Tf 0 0 0 sc 0 0 0 SC 0 Tr 013.47869.237
Package type 封装形式